Product / Package Information

Package	BGA_ED
Body Size (mm)	35 X 35
Ball Count	352
Terminal Finish	SnPb
Ball Size (mm)	0.76

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	9.45 E-03	75.0	750000	0.13	1295
Other organic materials	Resin	Proprietary	3.15 E-03	25.0	250000	0.04	432
Subtotal	Subtotal		1.26 E-02	100.0	1000000	0.17	1727

Heat Sink

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.21 E+00	100	1000000	71.33	713338

Heat Sink Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	2.24 E-01	99.9	1000000	3.07	30738

Laminate

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	9.86 E-02	18.30	183000	1.35	13517
Glass	Fiber Glass	65997-17-3	1.43 E-01	26.55	265500	1.96	19611
Thermoset	Organic resin	13676-54-5	1.75 E-01	32.45	324500	2.40	23969
	Laminate Core Subtotal		4.17 E-01	77.30	773000	5.71	57098
Other organic materials	Organic resin	Proprietary	7.40 E-02	13.72	137200	1.01	10134
Other inorganic materials	Inorganic Filler	Proprietary	3.98 E-02	7.39	73900	0.55	5459
	Soldermask Subtotal		1.14 E-01	21.11	211100	1.56	15593
Nickel & its alloys	Nickel	7440-02-0	6.47 E-03	1.20	12000	0.09	886
Precious Metals	Gold	7440-57-5	2.10 E-03	0.39	3900	0.03	288
Subtotal			5.39 E-01	100.00	1000000	7.39	73865

Solder Ball

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.31 E-01	63.00	630000	5.90	59045
Tin & its alloys	Lead	7439-92-1	2.53 E-01	37.00	370000	3.47	34677
Subtotal			6.84 E-01	100	1000000	9.37	93722

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.28 E-01	100	1000000	1.76	17569

Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	3.04 E-02	99.99	1000000	0.42	4166

Mold Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Epoxy	25068-38-6	3.43 E-01	72.5	725000	4.70	47034
Other organic materials	Silicon dioxide	60676-86-0	1.30 E-01	27.5	275000	1.78	17841
Subtotal			4.73 E-01	100.0	1000000	6.49	64875

	Weight (g)	Percentage (%)	PPM
Package Totals	**7.30 E+00**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.

ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary